ABSTRACT

HANDLING SYSTEM FOR INSPECTING AND SORTING ELECTRONIC COMPONENTS

A semiconductor package handling system is provided comprising a package holder for receiving and holding singulated semiconductor packages, and a first inspection device which is arranged and configured to inspect a first surface of the packages while they are being held by the package holder. An offloading device receives the packages from the package holder and conveys them packages to an offloader, and a second inspection device is arranged and configured to inspect a second surface of the packages which is opposite from the first surface while they are being held by the offloading device.

(FIG. 1)